


AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-12 (canceled). 

Claim 13 (currently amended): A lid material for a lid which is to be fuse-bonded to a peripheral upper surface of a case having an open top and a housing space for an electronic component, the lid material comprising:

a core layer;

a nickel-based metal layer ~~press- and diffusion-bonded onto the core layer and~~ composed of a nickel-based metal mainly comprising nickel, an entire thickness of the nickel-based metal layer being press- and diffusion-bonded onto the core layer; and

a brazing material layer press-bonded onto the nickel-based metal layer,

wherein the nickel-based metal layer has a maximum-to-minimum thickness ratio T1/T2 of 1.4 to 15.

Claim 14 (original): A lid material as set forth in claim 13, wherein the core layer is composed of an iron-nickel-based alloy mainly comprising iron and nickel.

Claim 15 (original): A lid material as set forth in claim 13, wherein the brazing material layer is composed of a soft brazing material having a melting point of not higher than 450°C.

Claim 16 (original): A lid material as set forth in claim 14, wherein the brazing material layer is composed of a soft brazing material having a melting point of not higher than 450°C.

Claim 17 (original): A lid material as set forth in claim 15, wherein the soft brazing material is free from lead.

Claim 18 (original): A lid material as set forth in claim 16, wherein the soft brazing material is free from lead.

Claim 19 (currently amended): An electronic component package comprising:
a case having an open top and a housing space for an electronic component;
and

a lid provided on the top of the case,

A2 the lid comprising a core layer, a nickel-based metal layer ~~press- and diffusion-~~
~~bonded onto the core layer and~~ composed of a nickel-based metal mainly comprising
nickel, an entire thickness of the nickel-based metal layer being press- and diffusion-
bonded onto the core layer, and a brazing material layer press-bonded onto the nickel-
based metal layer, the nickel-based metal layer having a maximum-to-minimum
thickness ratio $T1/T2$ of 1.4 to 15,

wherein the brazing material layer of the lid is fuse-bonded to a peripheral upper
surface of the case.

Claim 20 (original): An electronic component package as set forth in claim 19,
wherein the core layer is composed of an iron-nickel-based alloy mainly comprising iron
and nickel.

Claim 21 (original): An electronic component package as set forth in claim 19,
wherein the brazing material layer is composed of a soft brazing material having a
melting point of not higher than 450°C.

Claim 22 (original): An electronic component package as set forth in claim 20,
wherein the brazing material layer is composed of a soft brazing material having a
melting point of not higher than 450°C.

Claim 23 (original): An electronic component package as set forth in claim 21, wherein the soft brazing material is free from lead.

Claim 24 (original): An electronic component package as set forth in claim 22, wherein the soft brazing material is free from lead.

Claim 25 (new): A lid material as set forth in claim 13, wherein the brazing material layer is roll-pressed onto the nickel-based metal layer.

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Claim 26 (new): A lid material as set forth in claim 13, wherein the nickel-based metal layer has an average thickness of about 5 μm to about 50 μm .

Claim 27 (new): An electronic component package as set forth in claim 19, wherein the brazing material layer is roll-pressed onto the nickel-based metal layer.

Claim 28 (new): An electronic component package as set forth in claim 19, wherein the nickel-based metal layer has an average thickness of about 5 μm to about 50 μm .
